

IN THE CLAIMS:

Claims 1-20 have been amended herein. All of the pending claims 1 through 20 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) ~~In a~~A wire bonding apparatus for bonding a wire to a bond pad located on a ~~semiconductor~~semiconductor chip and a lead finger of a lead frame of a plurality of lead frames being supplied to ~~said wire~~the wire bonding apparatus in a strip form, ~~said the~~the apparatus comprising:

a wire bonding apparatus having a portion thereof for dispensing ~~of said the~~the wire to be bonded to ~~said the~~the bond pad and ~~said the~~the lead finger and bonding ~~said the~~the wire to ~~said the~~the bond pad or ~~said the~~the lead finger;

an independent clamp for engaging ~~another~~a portion of ~~said the~~the lead finger before ~~said~~said bonding of ~~said the~~the wire thereto, ~~said the~~the independent clamp being independently movable in relation to movement of another portion of ~~said the wire~~the wire bonding apparatus and ~~said the~~the lead finger of ~~said the~~the lead frame for engaging a portion of ~~said the~~the lead finger; and

a conventional fixed clamp for engaging another portion of ~~said the~~the lead finger adjacent ~~said the~~the independent clamp.

2. (Currently Amended) The apparatus of claim 1, wherein ~~said the~~the independent clamp is located between ~~said the wire~~the wire bonding apparatus and ~~said the~~the conventional fixed clamp for engaging ~~said the~~the portion of ~~said the~~the lead finger during ~~said~~said bonding of ~~said the~~the wire thereto.

3. (Currently Amended) The apparatus of claim 1, wherein ~~said the~~the independent clamp includes having an ability to move independently in an x-axis direction, y-axis direction and z-axis direction.

4. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the independent clamp is movable independently in any direction of a movement of ~~said~~ the wire bonding apparatus.

5. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the apparatus further comprises:
heating apparatus located beneath ~~said~~ the semiconductor chip.

6. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the apparatus further comprises:
heating apparatus located beneath ~~said~~ the lead finger.

7. (Currently Amended) The apparatus of claim 6, wherein ~~said~~ the semiconductor chip is heated before ~~said~~ the wire is bonded thereto.

8. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the independent clamp is resiliently mounted.

9. (Currently Amended) The apparatus of claim 8, wherein ~~said~~ the independent clamp is resiliently mounted through use of a spring engaging a portion of ~~said~~ the independent clamp.

10. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the independent clamp has an end portion thereof which is insulated.

11. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the independent clamp has an end portion thereof which is semicircular in shape.

12. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the independent clamp has an end portion thereof which is arcuate in shape.

13. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the independent clamp has an end portion thereof which is articulated for movement.

14. (Currently Amended) The apparatus of claim 1, wherein ~~said~~ the independent clamp is located between ~~said~~ the wire bonding apparatus and ~~said~~ the conventional fixed clamp engaging ~~said~~ the portion of ~~said~~ the lead finger during ~~said~~ bonding of ~~said~~ the wire thereto.

15. (Currently Amended) A wire bonding apparatus for bonding a wire to a bond pad located on a semiconductor chip and a lead finger of a lead frame of a plurality of lead frames supplied to ~~said~~ the wire bonding apparatus in a strip form, ~~said~~ the apparatus comprising:
wire bonding apparatus having a portion thereof for dispensing ~~of~~ ~~said~~ the wire to be bonded to ~~said~~ the bond pad and ~~said~~ the lead finger and bonding ~~said~~ the wire to ~~said~~ the bond pad or ~~said~~ the lead finger;
a conventional fixed clamp for engaging a portion of ~~said~~ the lead finger; and
an independent clamp for engaging another portion of ~~said~~ the lead finger before ~~said~~ bonding of ~~said~~ the wire thereto, ~~said~~ the independent clamp having an ability to move as desired in an x-axis ~~direction~~ direction, a y-axis direction, and a z-axis direction concurrently regarding a portion of ~~said~~ the lead finger and being independently movable in relation to movement of another portion of ~~said~~ the wire bonding apparatus.

16. (Currently Amended) The apparatus of claim 15, wherein ~~said~~ the independent clamp is movable independent of a movement of ~~said~~ the wire bonding apparatus.

17. (Currently Amended) The apparatus of claim 15, wherein ~~said~~ the apparatus further comprises:
heating apparatus located beneath ~~said~~ the semiconductor chip.

18. (Currently Amended) The apparatus of claim 17, wherein ~~said~~ the apparatus further comprises:
heating apparatus located beneath ~~said~~ the lead finger.

19. (Currently Amended) The apparatus of claim 17, wherein ~~said~~ the semiconductor chip is heated before ~~said~~ the wire is bonded thereto.

20. (Currently Amended) The apparatus of claim 15, wherein ~~said~~ the independent clamp is resiliently mounted.